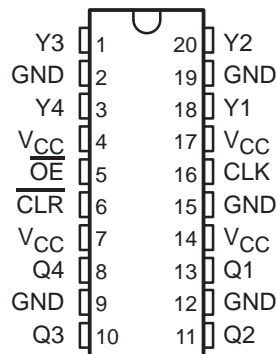


CDC337 CLOCK DRIVER WITH 3-STATE OUTPUTS

SCAS330B – DECEMBER 1990 – REVISED OCTOBER 1998

- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and CMOS-Compatible Outputs
- Distributes One Clock Input to Eight Outputs
 - Four Same-Frequency Outputs
 - Four Half-Frequency Outputs
- Distributed V_{CC} and Ground Pins Reduce Switching Noise
- High-Drive Outputs ($-48\text{-mA } I_{OH}$, $48\text{-mA } I_{OL}$)
- State-of-the-Art *EPIC-II B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW)

DW PACKAGE
(TOP VIEW)



description

The CDC337 is a high-performance, low-skew clock driver. It is specifically designed for applications requiring synchronized output signals at both the clock frequency and one-half the clock frequency. The four Y outputs switch in phase and at the same frequency as the clock (CLK) input. The four Q outputs switch at one-half the frequency of CLK.

When the output-enable (\overline{OE}) input is low and the clear (\overline{CLR}) input is high, the Y outputs follow CLK and the Q outputs toggle on low-to-high transitions at CLK. Taking \overline{CLR} low asynchronously resets the Q outputs to the low level. When \overline{OE} is high, the outputs are in the high-impedance state.

The CDC337 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUTS			OUTPUTS	
\overline{OE}	\overline{CLR}	CLK	Y1–Y4	Q1–Q4
H	X	X	Z	Z
L	L	L	L	L
L	L	H	H	L
L	H	L	L	Q_0^{\dagger}
L	H	\uparrow	H	\overline{Q}_0^{\dagger}

[†] The level of the Q outputs before the indicated steady-state input conditions were established



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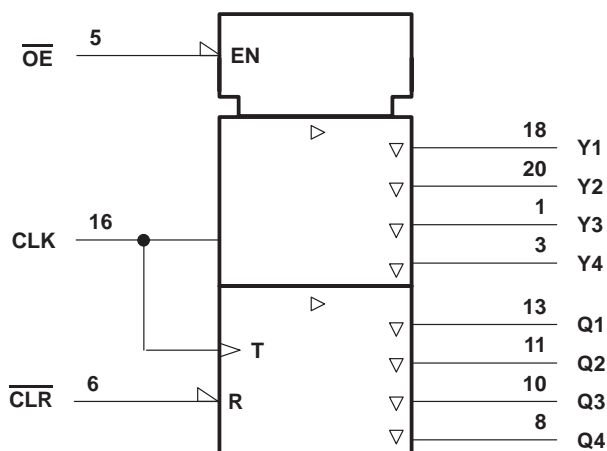
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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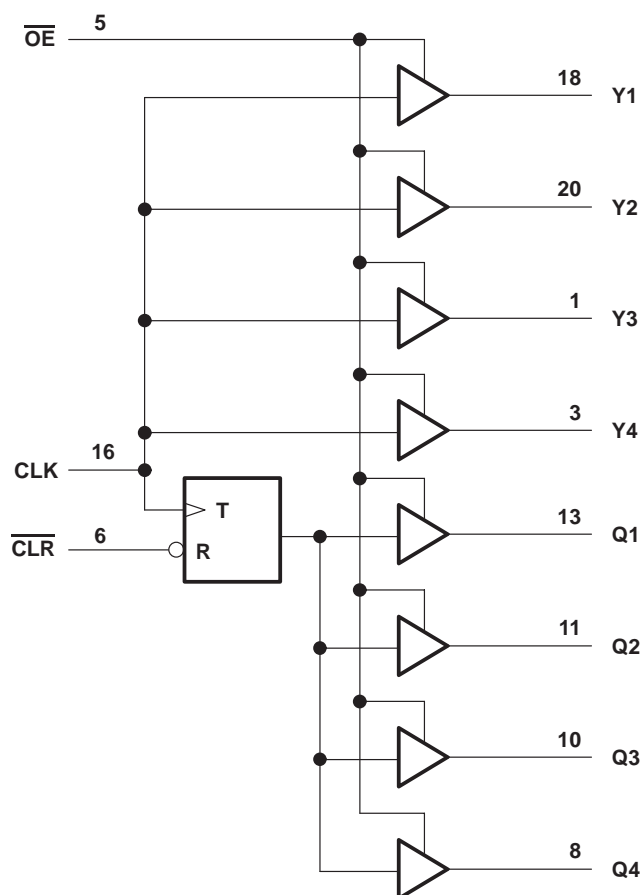
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O	96 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2)	1.6 W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

CDC337 CLOCK DRIVER WITH 3-STATE OUTPUTS

SCAS330B – DECEMBER 1990 – REVISED OCTOBER 1998

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4.75	5.25	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
I_{OH}	High-level output current		–48	mA
I_{OL}	Low-level output current		48	mA
f_{clock}	Input clock frequency		80	MHz
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}	V _{CC} = 4.75 V, I _I = −18 mA				−1.2	V
V _{OH}	V _{CC} = 4.75 V, I _{OH} = −32 mA		3.75			V
V _{OL}	V _{CC} = 4.75 V, I _{OL} = 32 mA				0.55	V
I _{IH}	V _{CC} = 5.25 V, V _I = 2.7 V				50	μA
I _{IL}	V _{CC} = 5.25 V, V _I = 0.5 V				−50	μA
I _{OZ}	V _{CC} = 5.25 V, V _O = V _{CC} or GND				±50	μA
I _{CC}	V _{CC} = 5.25 V, V _I = V _{CC} or GND, I _O = 0	Outputs high			70	mA
		Outputs low			85	
		Outputs disabled			70	
C _i	V _I = 2.5 V or 0.5 V			3		pF
C _O	V _O = V _{CC} or GND			10		pF

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		MIN	MAX	UNIT
f_{clock}	Clock frequency		80	MHz
t_w	Pulse duration	CLR low	4	ns
		CLK low	4	
		CLK high	4	
t_{su}	Setup time, $\overline{\text{CLR}}$ inactive before CLK↑		2	ns
	Clock duty cycle	40%	60%	



CDC337

CLOCK DRIVER

WITH 3-STATE OUTPUTS

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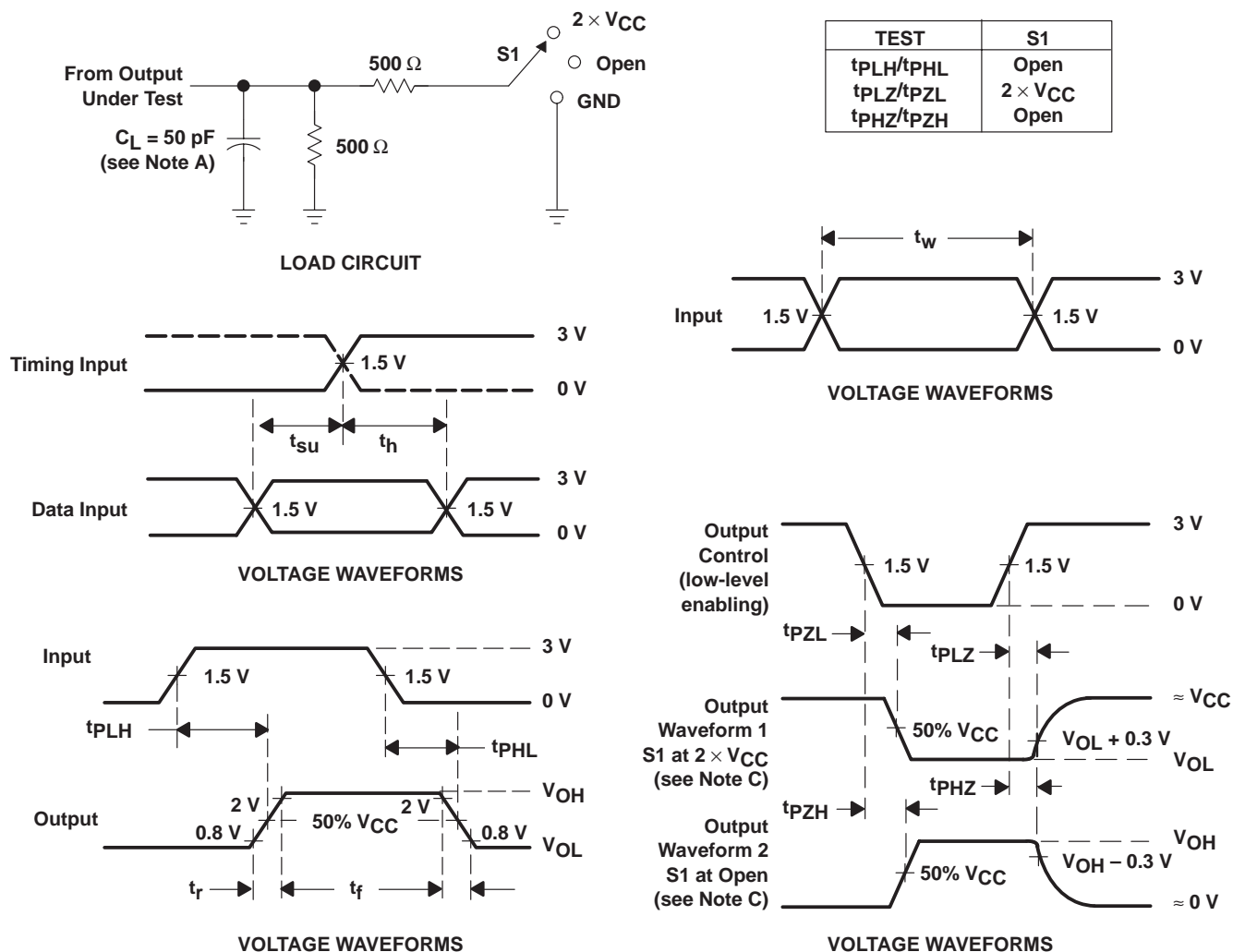
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Note 4 and Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP†	MAX	UNIT
f_{max}			80			MHz
t_{PLH}	CLK	Any Y or Q	4		9	ns
t_{PHL}			4		9	
t_{PHL}	\overline{CLR}	Any Q	4		10	ns
t_{PZH}	\overline{OE}	Any Y or Q	3		7	ns
t_{PZL}			3		7	
t_{PHZ}	\overline{OE}	Any Y or Q	2		7	ns
t_{PLZ}			2		7	
$t_{sk(o)}$	CLK↑	Y↑			0.75	ns
		Q↑			0.9	
		Y↑ and Q↑			0.9	
t_r				0.9		ns
t_f				0.7		ns

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

NOTE 4: All specifications are valid only for all outputs switching.

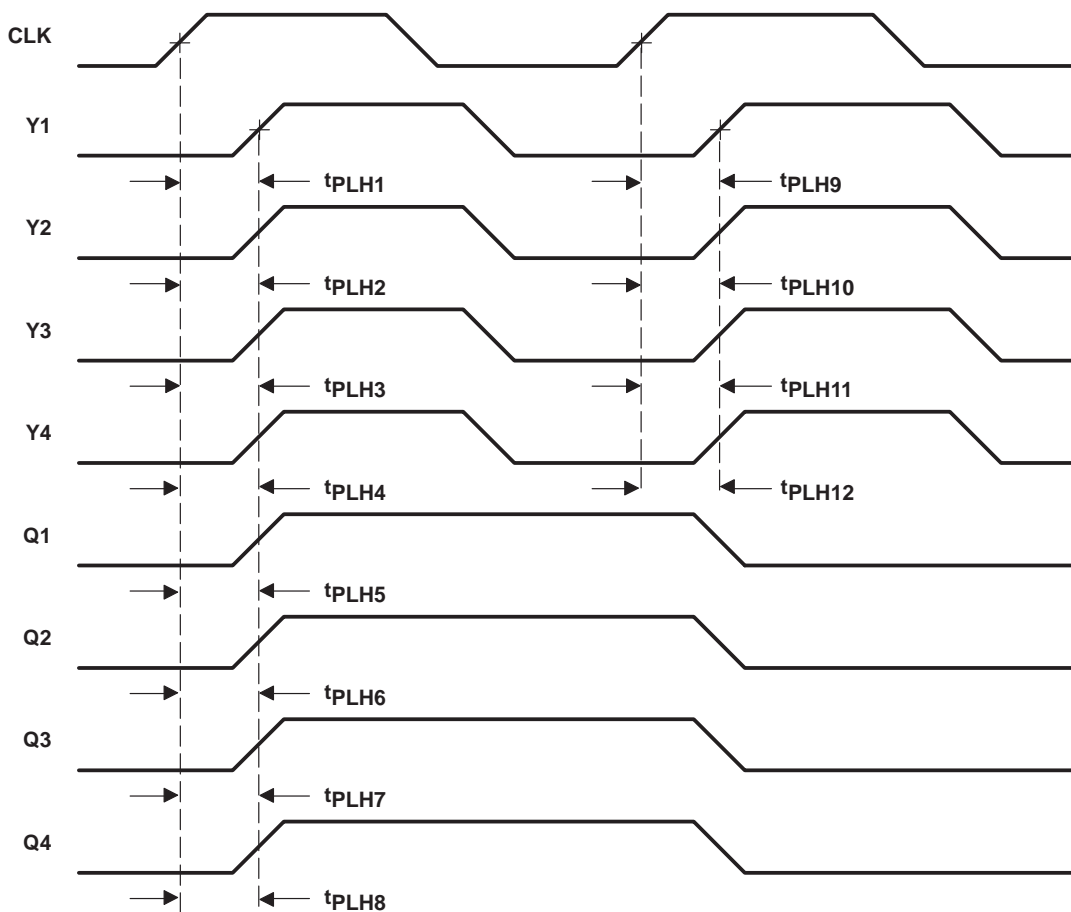
PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew, $t_{sk(o)}$, from $CLK\uparrow$ to $Y\uparrow$, is calculated as the greater of the difference between the fastest and slowest of t_{PLHn} ($n = 1, 2, 3, 4$) or t_{PLHn} ($n = 9, 10, 11, 12$).
- B. Output skew, $t_{sk(o)}$, from $CLK\uparrow$ to $Q\uparrow$, is calculated as the greater of the difference between the fastest and slowest of t_{PLHn} ($n = 5, 6, 7, 8$).
- C. Output skew, $t_{sk(o)}$, from $CLK\uparrow$ to $Y\uparrow$ and $Q\uparrow$, is calculated as the greater of the difference between the fastest and slowest of t_{PLHn} ($n = 1, 2, \dots, 8$).

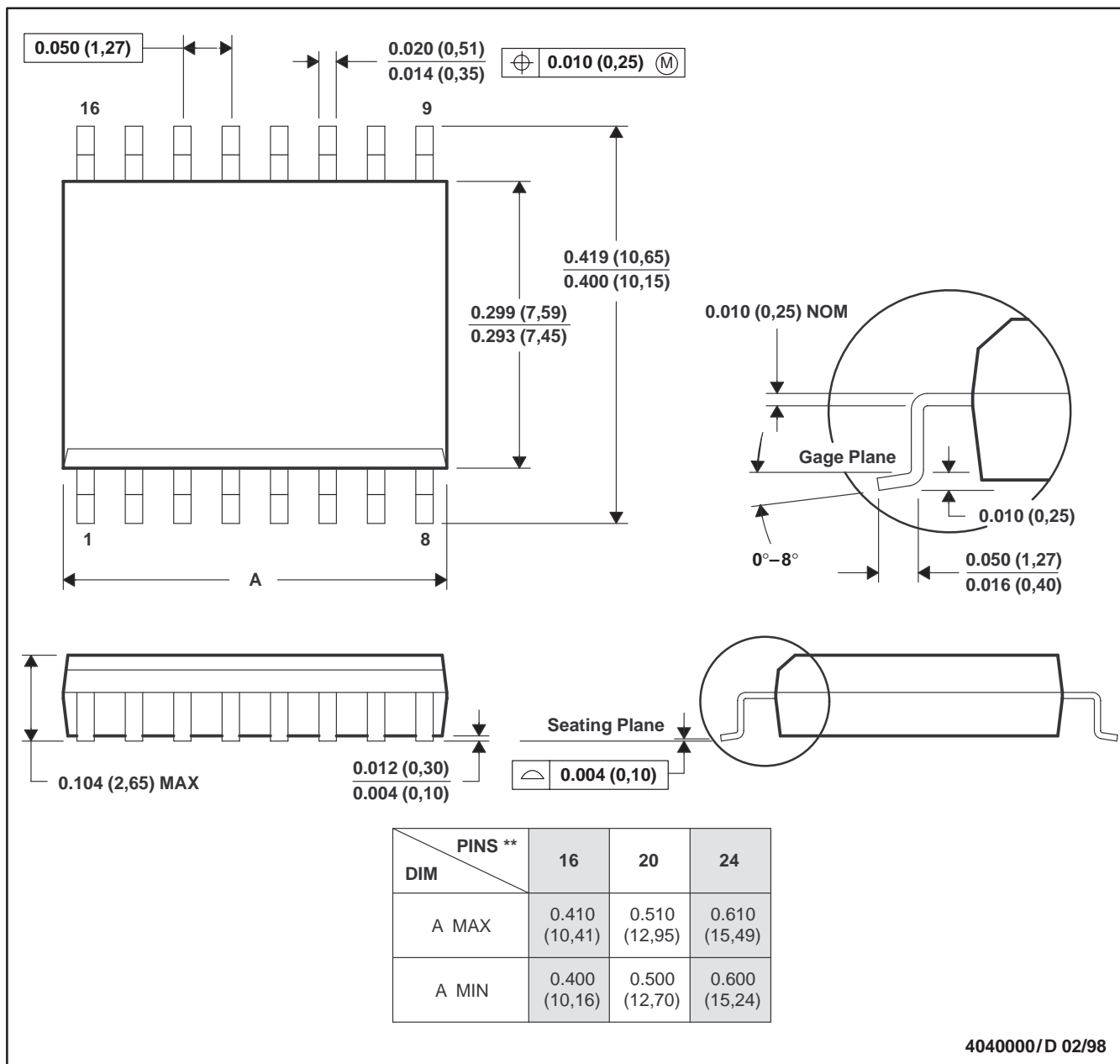
Figure 2. Waveforms for Calculation of $t_{sk(o)}$

MECHANICAL INFORMATION

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CDC337DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	Samples Not Available
CDC337DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Request Free Samples
CDC337DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Request Free Samples
CDC337DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CDC337DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CDC337NS	OBSOLETE	SO	NS	20		TBD	Call TI	Call TI	Samples Not Available
CDC337NSG4	OBSOLETE	SO	NS	20		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

7-Jun-2010

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC337DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC337DWR	SOIC	DW	20	2000	367.0	367.0	45.0

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